

**IN THE CLAIMS**

Please cancel claims 1-15, and add new independent claims 16-19 as shown below.

Claim 16. (New) A chemical oxide film removing method of removing a silicon dioxide film formed on a surface of a workpiece in a processing vessel that can be evacuated, the silicon dioxide film being a chemical oxide film that has been formed by a chemical process using a solution prepared by mixing H<sub>2</sub>O<sub>2</sub> and NH<sub>4</sub>OH,

wherein the chemical oxide film is removed under conditions that:

a mixed gas containing HF gas and NH<sub>3</sub> gas is used;

a processing temperature for achieving etch selectivity for the chemical oxide film to silicon is in the range of 200°C to 400°C;

a processing pressure at which the workpiece is processed is in the range of 26 Pa (0.2 Torr) to 53,200 Pa (400 Torr); and

the flow rate ratio of HF gas to NH<sub>3</sub> gas is in the range of 10 : 1 to 1 : 50.

Claim 17. (New) A chemical oxide film removing method of removing a silicon dioxide film formed on a surface of a workpiece in a processing vessel that can be evacuated, the silicon dioxide film being a chemical oxide film that has been formed by a chemical process using a solution prepared by mixing H<sub>2</sub>O<sub>2</sub> to NH<sub>4</sub>OH,

wherein the chemical oxide film is removed under conditions that:

a mixed gas containing HF gas and NH<sub>3</sub> gas is used;

a processing temperature for achieving etch selectivity for the chemical oxide film to a silicon nitride film is in the range of 200°C to 600°C;

a processing pressure at which the workpiece is processed is not more than 53,200 Pa (400 Torr); and

the flow rate ratio of HF gas to NH<sub>3</sub> gas is in the range of 10 : 1 to 1 : 50.

Claim 18. (New) A chemical oxide film removing method of removing a silicon dioxide film formed on a surface of a workpiece in a processing vessel that can be evacuated, the silicon dioxide film being a chemical oxide film that has been formed by a chemical process using a solution prepared by mixing H<sub>2</sub>O<sub>2</sub> and NH<sub>4</sub>OH,

wherein the chemical oxide film is removed under conditions that:

a mixed gas containing HF gas and NH<sub>3</sub> gas is used;

a processing temperature for achieving etch selectivity for the chemical oxide film to a silicon dioxide film, which has been formed by CVD (Chemical Vapor Deposition), is in the range of 200°C to 400°C;

a processing pressure at which the workpiece is processed is not more than 53,200 Pa (400 Torr); and

the flow rate ratio of HF gas to NH<sub>3</sub> gas is in the range of 10 : 1 to 1 : 50.

Claim 19. (New) A chemical oxide film removing method of removing a silicon dioxide film formed on a surface of a workpiece in a processing vessel that can be evacuated, the silicon dioxide film being a chemical oxide film that has been formed by a chemical process using a solution prepared by mixing H<sub>2</sub>O<sub>2</sub> and NH<sub>4</sub>OH,

wherein the chemical oxide film is removed under conditions that:

a mixed gas containing HF gas and NH<sub>3</sub> gas is used;

a processing temperature for achieving etch selectivity for the chemical oxide film to a thermal oxide film is in the range of 100 °C to 600 °C;

a processing pressure at which the workpiece is processed is not more than 53,200 Pa (400 Torr); and

the flow rate ratio of HF gas to NH<sub>3</sub> gas is in the range of 10 : 1 to 1 : 50.